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(54) **ELECTRONIC DEVICE AND  
MANUFACTURING METHOD THEREOF**

(71) Applicant: **FUJIFILM Corporation**, Tokyo (JP)

(72) Inventor: **Yusuke FUJII**, Kanagawa (JP)

(73) Assignee: **FUJIFILM Corporation**, Tokyo (JP)

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**ABSTRACT**

Provided are an electronic device including: a wiring board having a mounting surface; a ground electrode that defines a ground region on the mounting surface; an electronic component that is located on the mounting surface and is disposed in the ground region; a conductive component that is disposed adjacent to an outer edge of the ground electrode; an internal insulating protective layer that is disposed in the ground region and covers the electronic component; an external insulating protective layer that is disposed outside the ground region and covers the conductive component; and an electromagnetic wave shielding layer that is provided to extend over the internal insulating protective layer and the ground electrode and that covers the internal insulating protective layer and is electrically connected to the ground electrode, the electromagnetic wave shielding layer being a solidified product of an ink for forming an electromagnetic wave shielding layer, and a manufacturing method thereof.

